PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16018
1.3 Title of PCN	ST Shenzhen (China) additional source for STM32F2x and STM32F4x listed products in LQFP 20x20 and LQFP 24x24 packages.
1.4 Product Category	STM32F205x, STM32F215x, STM32F207x, STM32F217x, STM32F405x, STM32F415x, STM32F407x, STM32F417x, STM32F429x, STM32F439x, STM32F427x and STM32F437x
1.5 Issue date	2026-04-21

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ST Shenzhen (China)

4. Description of change

	Old	**New**
4.1 Description	Current assembly sites (depending on package): - AMKOR ATP (Philippine) Gold wire, - AMKOR ATP (Philippine) Copper Palladium wire, - ASE Kaohsiung (Taiwan) Gold wire , - ASE Kaohsiung (Taiwan) Copper Palladium wire , You may refer to 16018_Additional information.pdf document for further details.	Current assembly sites: (depending on package) : - AMKOR ATP (Philippine) Gold , - AMKOR ATP (Philippine) Copper Palladium wire , - ASE Kaohsiung (Taiwan) Gold wire , - ASE Kaohsiung (Taiwan) Copper Palladium wire , Additional assembly site for extended capacity: - ST Shenzhen (China) Copper Alloy wire .
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact on Form, Fit or Function	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Change is visible on the marking Assembly Site code . • GK : ST Shenzhen (China) new assembly site • 7B : AMKOR ATP (Philippines) • AA : ASE KaoHsiung (Taiwan) Please refer to PCN 16018_Additional information.pdf document for further details.

7. Timing / schedule

7.1 Date of qualification results	2026-06-22
7.2 Intended start of delivery	2026-06-25
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16018 MDRF-GPAM-RER2506 PCN16018 - ST Shenzhen LQFP 20x20_24x24 packages - reliab plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2026-04-21

9. Attachments (additional documentations)

16018 Public product.pdf
16018 MDRF-GPAM-RER2506 PCN16018 - ST Shenzhen LQFP 20x20_24x24 packages - reliab plan.pdf
16018 _Additional information.pdf

10. Affected parts

10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32F205ZCT6	
	STM32F205ZCT6TR	
	STM32F205ZCT7	
	STM32F205ZCT7TR	
	STM32F205ZET6	
	STM32F205ZET6TR	
	STM32F205ZET7	
	STM32F205ZET7TR	
	STM32F205ZFT6	
	STM32F205ZGT6	
	STM32F205ZGT6TR	
	STM32F205ZGT7	
	STM32F207ICT6	
	STM32F207IET6	
	STM32F207IFT6	
	STM32F207IGT6	
	STM32F207IGT7	
	STM32F207ZCT6	
	STM32F207ZCT7	
	STM32F207ZCT7TR	
	STM32F207ZET6	
	STM32F207ZET6TR	
	STM32F207ZFT6	
	STM32F207ZGT6	
	STM32F207ZGT6TR	
	STM32F207ZGT7	
	STM32F215ZET6	
	STM32F215ZGT6	
	STM32F215ZGT7TR	
	STM32F217IET6	
	STM32F217IGT6	
	STM32F217IGT7	
	STM32F217ZET6	
	STM32F217ZGT6	

	STM32F405ZGT6	
	STM32F405ZGT7	
	STM32F407IET6	
	STM32F407IGT6	
	STM32F407IGT7	
	STM32F407ZET6	
	STM32F407ZET7	
	STM32F407ZGT6	
	STM32F407ZGT6TR	
	STM32F407ZGT7	
	STM32F415ZGT6	
	STM32F417IET6	
	STM32F417IGT6	
	STM32F417IGT7	
	STM32F417ZET6	
	STM32F417ZGT6	
	STM32F427IGT6	
	STM32F427IIT6	
	STM32F427IIT7	
	STM32F427ZGT6	
	STM32F427ZIT6	
	STM32F427ZIT6TR	
	STM32F427ZIT7	
	STM32F427ZIT7TR	
	STM32F429IET6	
	STM32F429IGT6	
	STM32F429IIT6	
	STM32F429ZET6	
	STM32F429ZET6TR	
	STM32F429ZGT6	
	STM32F429ZGT6TR	
	STM32F429ZIT6	
	STM32F429ZIT6TR	
	STM32F429ZIT7	
	STM32F437IGT6	
	STM32F437IIT6	
	STM32F437IIT7	
	STM32F437ZGT6	
	STM32F437ZIT6	
	STM32F437ZIT7	
	STM32F437ZIT7TR	
	STM32F439IGT6	
	STM32F439IIT6	
	STM32F439ZGT6	
	STM32F439ZIT6	

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